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Date: August 1, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Johann Winderl et al.
Applic. No. : 10/079,114 ✓
Filed : February 20, 2002
Title : Electronic Component with a Semiconductor Chip and Method of Producing an Electronic Component
Art Unit : 2811

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INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

Japanese Patent Abstract JP 02 114 946 A (Mori), dated June 4, 1990;

Japanese Patent Abstract JP 08 031 989 A (Ishikawa), dated February 2, 1996.

Respectfully submitted,

[Signature]

For Applicants

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